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Technical Papers

100 Gb/s Ethernet 100GBASE-CR4 Test Points and Test Fixtures
Christopher DiMinico (MC Communications), Mike Resso (Keysight Technologies), Mike Sapozhnikov (Cisco Systems)

56 Gb/s Serial Transmission using Duo-binary Signaling
Yu Ban (INTEC-IMEC), Johan Bauwelinck (Ghent University/iMinds), Jan De Geest (FCI), Timothy De Keulenaer (INTEC-IMEC), Bartek Kozicki (Alcatel-Lucent), Jeffrey Sinsky (Alcatel-Lucent), Guy Torfs (INTEC-IMEC)

A Brief Tour of FEC for Serial Link Systems
Shu Lin (University of California, Davis), Cathy Ye Liu (Avago Technologies), Michael Steinberger (Signal Integrity Software, Inc.)

A Cure for Intra-Pair Skew in High Speed Differential Signals Michael Jenkins (Xilinx)
A Fast and Accurate Approach to Power Integrity Analysis for complex SiP
Ashish Gupta (Ericsson BMOD), Sheetal Jain (Ericsson BMOD), Taranjit Kukal (Cadence)

A Fast Method And Practical Considerations For Stable System Level Time-Domain Simulation Including DDR SSO Analysis
Sam Karikalan (Broadcom), Namhoon Kim (Broadcom), Uttara Sampath (Broadcom), Dharmendra Saraswat (Broadcom)

A New Methodology for Developing IBIS-AMI Models
Pegah Alavi (Keysight Technologies), John Baprawski (johnbaprawski.com), Hongtao Zhang (Xilinx), Geoff Zhang (Xilinx)

A Novel Approach to Model Dynamic Noise in Static Timing Analysis
Dan Oh (Altera), Yujeong Shim (Altera)

A Novel Method To Reduce Differential Crosstalk In A High-Speed Channel
Kunia Aihara (Hirose Electric USA), Jeremy Buan (Hirose Electric USA), Ching-Chao Huang (AtaiTec Corporation), Bill MacKillop (Hirose Electric USA), Toshiyuki Takada (Hirose Electric)

A Novel Simulation Flow to Expand Uses of IBIS-AMI Models in Mixed Tool Environment
YL Li (Intel Corp.), Weifeng Shu (Intel Asia Pacific Research & Development Ltd.), Xiaoning Ye (Intel Corp), Chunfei Ye (Intel Corp.), Xinjun Zhang (Intel Asia Pacific Research & Development Ltd.)

A Novel Stressed Eye Tolerance Test Methodology using IBIS AMI Modeling Techniques
Venkatesh Avula (Seagate)

A Simple And Innovative Circuit Technique To Tackle Power Supply Induced Jitter In High Speed Serial Links For 25Gbps Transmission And Beyond
Dan Oh (Altera Corporation), Yujeong Shim (Altera Corporation)

A Simple Method To Characterize And Accurately Remove The Effects Of Push-On Connectors
Reiner Oppelt (Rosenberger Hochfrequenztechnik), Robert Schaefer (Keysight Technologies), Joachim Schubert (Rosenberger Hochfrequenztechnik)

A Systematic Merging and Isolation Strategy for I/O Power Integrity in Mobile Chipsets and Platforms
Kai Chow (NVIDIA Corporation), Daehyun Chung (NVIDIA Corporation), Mona Fahim (NVIDIA Corporation), Daniel Lin (NVIDIA Corporation), Nithya Sankaran (NVIDIA Corporation), Sunil Sudhakaran (NVIDIA Corporation)

Accurate Statistical Analysis Of Serdes Links Considering Correlated Input Patterns, Data-Dependent Edge Transitions, And Transmit Jitter
Vladimir Dmitriev Zdorov (Mentor Graphics)

Analytical Approaches for Worst and Statistical Eye Estimation in HBM Channel
Kiyeong Kim (KAIST), Jingook Kim (UNIST), Heegon Kim (KAIST), Hyungsoo Kim (SK Hynix), Joungho Kim (KAIST), Jiseong Kim (KAIST)

Anisotropic Design Considerations for 28 Gbps Via to Stripline Transitions
Scott McMorrow (Teraspeed Consulting - A Division of Samtec), Edward Sayre (Teraspeed Consulting, a division of Samtec Inc.)

At-Speed Testing of 32 Gbaud PAM-4 Interfaces using Automated Test Equipment
Volker Filsinger (SHF), Jose Moreira (Advantest), Hubert Werkmann (Advantest)

Augmenting Virtual Platform Simulations With Interface Electricals
Todd Bermensolo (Intel Corporation), Dan Crain (Intel Corporation), Zao Liu (Intel), Peter Njenga (Intel Corporation)

Behavioral Model Of On-Die Voltage Regulator For Soc Power Delivery Analysis
Jayong Koo (Intel), Xiaoping Liu (Intel Corporation), Ramnarayanan Muthukaruppan (Intel Corporation), Min Wang (Intel Corporation)

Behavioral Modeling of Random Jitter with Realistic Time and Frequency Dependence
Scott Wedge (Synopsys, Inc.)

Behavioral RX Model Correlation with Physical Devices, and Accuracy Improvement
Mike Peng Li (Altera), Timothy Lu (Altera), Masashi Shimanouchi (Altera), Hsinho Wu (Altera)

Breaking the 32 Gb/s Barrier: PCB Materials, Simulations, Measurements
Heidi Barnes (Keysight Technologies), Al Neves (Wild River Technology), Lee Ritchey (Speeding Edge), Tim Wang Lee (Wild River Technology)

Cascaded S-parameter or Combined 3DEM Modeling for DDR4 Memory Channel Design?
Hany Fahmy (Intelligent Solutions BVBA), Klaus Krohne (CST)

Causality Demystified
Chris Kocuba (Samtec), Jim Nadolny (Samtec), Stefaan Sercu (Samtec)

Characterization of PCB Insertion Loss with a New Calibration Method
Ning Cheng (Keysight Technologies), Gongxian Jia (Huawei Technologies), Faming Long (Huawei Technologies), Mike Resso (Keysight Technologies), Wenxue Zhu (Huawei)

Ciruit, SI, PI Co-Design of LPDDR4 and LPDDR3
Isaac Ali (Intel Corp.), Ritochit Chakraborty (Intel Corp.), Ge Chang (Intel), Almario F. Delos (Intel Corporation), Te-Yu (Jason) Kao (Intel Corp.), Vishram Pandit (Intel Corp), Ritesh B. Trivedi (Intel Corp.), Brian Wang (Intel Corp)

Co-Design for 1TB System Utilizing 33Gbps Transceivers in 20nm Technology
Ravindra Gali (Xilinx), Romi Mayder (Xilinx), Sarajuddin Niazi (Xilinx), Hong Shi (Xilinx)

Connectivity 2.0
Gary McCormack (Keyssa, Inc.)

Critical Memory Performance metrics for DDR4 systems
Barbara Aichinger (FuturePlus Systems)

DDR4 Board Design and Signal Integrity Verification Challenges
Nitin Bhagwath (Mentor Graphics Corporation), Chuck Ferry (Mentor Graphics Corporation), Motoaki Matsumura (Fujitsu Semiconductor Ltd.), Akihiro Miki (Fujitsu VLSI Ltd.), Arpad Muranyi (Mentor), Atsushi Sato (Fujitsu Semiconductor Ltd.), Randy Wolff (Micron Technology, Inc.)

Design and Characterization of a Low-Power, 6.4 Gbps Data Rate DDR Memory Interface System
Scott Best (Rambus Inc.), Michael Bucher (Rambus Inc.), Liji Gopalakrishnan (Rambus Inc.), Ravi Kollipara (Rambus), Ganapathy E. Kumar (Rambus Inc.), Hai Lan (Rambus Inc.), Lei Luo (Rambus Inc.), Chris Madden (Rambus Inc.), Kashinath Prabhu (Rambus Inc.), Pravin K. Venkatesan (Rambus Inc.)

Design and Characterization of Interconnects for Serial Links Operating at 56 Gbps and Beyond
Yeon-Chang Hahm (Rambus), Wendem Beyene (Rambus), Narayanan Mayandi (Rambus Inc.), Don Mullen (Rambus), Dave Secker (Rambus)

Design and Simulation of Equalizer Adaptation Engine in Multi-Protocol Serial Links
Wendem Beyene (Rambus Inc.), Simon Li (Rambus Inc.), Nikhil Vaidya (Rambus Inc.), Roxanne Vu (Rambus Inc.), Arash Zargaran Yazd (Rambus Inc.)

Design and Verification for High-Speed I/Os at Multiple to 60 Gbps With Jitter, Signal Integrity, and Power Optimization
Mike Peng Li (Altera)

Designing High Performance Interposers with 3-Port And 6-Port S-Parameters
Jonathan Dandy (Tektronix), Phillip Pun (Cadence), Joseph Socha (Nexus Technology), Prashanth Thota (Tektronix)

Development of Low Transmission Loss Multi Wire Board
Hiroyuki Yamaguchi (Hitachi Chemical Co.,Ltd.)

Does Skew Really Degrade SERDES Performance?
Gustavo Blando (Oracle), Shirin Farrahi (Oracle), Vijay Kunda (Oracle), Istvan Novak (Oracle), Li Ying (Oracle), Xun Zhang (Oracle Corporation)

Effective Analysis Methodology for Reducing Power Management Integrated Circuit (PMIC) Coupling Noise in Mobile System Dongho Yu (Samsung Electronics)

Effective Roughness Dielectric To Represent Copper Foil Roughness In Printed Circuit Boards
Marina Koledintseva (Oracle)

Effects of Component Resonance on High-Speed Channel Performance
Madhumitha Rengarajan (FCI USA LLC), Stephen Smith (FCI USA LLC), Andrew Zambell (FCI USA LLC)

Effects of Device Characteristics in Multi-Level Signaling Links
Mike Peng Li (Altera Corp.), Masashi Shimanouchi (Altera Corp.), Hsinho Wu (Altera Corp.)

Efficient Analog and Mixed Signal Modeling using Digital Simulation Charles Geer (IBM)
Electrodeposited Copper Foil Surface Characterization for Accurate Conductor Loss Modeling
Michael Griesi (University of South Carolina)

Electromagnetic Noise Effects on Semiconductor System in Electric Vehicle
Bumhee Bae (KAIST), Daniel Jung (KAIST), Jonghoon Kim (KAIST), Sukjin Kim (KAIST), Joungho Kim (KAIST), Sunkyu Kong (KAIST)

EMI Analysis of High-Speed I/O Connector in a Active System
Alpesh Bhobe (Cisco Systems Inc.), Xiao Li (Cisco Systems Inc.), Michael Rowlands (Molex)

Energy Proportional Power Management for Datacenter Applications
Uday Ammu (Google Inc), Neilus O'Sullivan (Google Inc), Mobashar Yazdani (Google Inc)

Everything About S Parameters: Tips and Tricks for Correct Usage
Dr. John Dunn (AWR)

Evolution of Tranceiver Jitter and Noise Modeling in Behavioral Link Simulation
Mike Peng Li (Altera), Timothy Lu (Altera), Masashi Shimanouchi (Altera), Hsinho Wu (Altera)

Extending the Reach of VCSEL Based 100 Gb/s Multimode Parallel Optic Links
Waruna Fernando (Avago Technologies), John Wilks (Avago Technologies)

Fast Statistical Eye-Diagram Estimation For High-Speed Channel Including Receiver Circuit
Heegon Kim (KAIST), Kiyeong Kim (KAIST), Jingook Kim (UNIST), Hyungsoo Kim (SK Hynix), Joungho Kim (KAIST), Changwook Yoon (Altera)

Frequency-Dependent Input/Output Capacitance Of High Speed Serial IOs
Mo Liu (Intel), Jongbae Park (Intel), William R Peters (Intel), Russell Norman Shryock (Intel), Jennifer Tsai (Intel)

Full-Wave Simulation vs. Multi-line S-Parameter Concatenation for Analysis at Frequencies up to 50 GHz
Stephen Smith (FCI USA LLC), Jeffrey Walden (EMC/SI RF, LLC)

Getting Street-Smart about S Parameters
Richard Allred (Signal Integrity Software, Inc.), Peter LaFlamme (Signal Integrity Software, Inc.), Michael Mayer (Signal Integrity Software, Inc.), Michael Steinberger (Signal Integrity Software, Inc.), Todd Westerhoff (Signal Integrity Software, Inc.)

High-Performance Enabling Parallel Buses for Exascale Systems
Gil Aguiar (NTK Technologies), Christian Baks (IBM Corporation), Noritaka Ban, Ph.D (NTK Technologies), Dr. Timothy Chainer, Ph.D (IBM Corporation), Michael Gaynes (IBM Corporation), Masakazu Hashimoto (Zeon Corporation), Dr. Manabu Hoshino, Ph.D (Zeon Corporation), Toshihiko Jimbo, Ph.D (Zeon Corporation), Junji Kodemura (Zeon Corporation), Atsushi Kuhara, Ph.D (NTK Technologies), Dr. Young Kwark, Ph.D (IBM Corporation), Aravind Nayak (Avago Technologies), Yoshiki Nukayam, Ph.D (NTK Technologies), Hajime Saiki, Ph.D (NTK Corporation), Lei Shan (IBM Corporation), Takuya Torii, Ph.D (NTK Technologies), Dr. Haitao (Tony) Xia (Avago Technologies)

High-Speed Low-Power On-Chip Global Signaling Design Overview
Rizwan Bashirullah (University of Florida), Xi Chen (NVIDIA), Tom Gray (NVIDIA), John Poulton (NVIDIA), John Wilson (NVIDIA)

Hybrid Modeled Measured Characterization of a 320 Gbit/s Backplane System
Josiah Bartlett (Tektronix), Sarah Boen (Tektronix), Ed Ford (Tektronix)

IBIS-AMI Model Simulations over Six EDA Platforms
Brandon Jiao (Xilinx), Ivan Madrigal (Xilinx), Romi Mayder (Xilinx), Hongtao Zhang (Xilinx), Geoff Zhang (Xilinx)

IBIS-AMI Modeling and Simulation of 56G PAM4 Link Systems
Xiaoqing Dong (Huawei), Fangyi Rao (Keysight Technologies), Hongtao Zhang (Xilinx), Geoff Zhang (Xilinx Inc)

Impact of Regulator Sense-point Location on PDN Response
Joseph 'Abe' Hartman (Oracle), Kavitha Narayandass (Oracle), Istvan Novak (Oracle)

Impedance Measurement and Relating it to Control Loop Stability
Steve Sandler (Picotest)

Jitter Failure Investigation Of High Speed Parallel Links In System On Chip Environment, Modeling And Mitigation Approach
Pratik Damle (STMicroelectronics), Rakesh Malik (STMicroelectronics), Jayanta Mukherjee (Indian Institute of Technology Bombay), Raj Kumar Nagpal (STMicroelectronics), Dr. Jai Narayan Tripathi (STMicroelectronics)

Method to Reduce Coupon Length for S-parameter Measurements
Shaowu Huang (Intel Corporation), Richard Kunze (Intel Corporation), Jeff Loyer (Intel Corporation), Boping Wu (Intel Corporation)

Minimization of Electromagnetic Interference Between PCB Antennas and Digital Interfaces
Mehdi Mechaik (IBM)

Mitigation of Fiber-Weave Effects by Broadside-Coupled Differential Striplines
Tomoyuki Akahoshi (Fujitsu Laboratories LTD.), Teng-Kai Chen (Molex), Taiga Fukumori (Fujitsu Laboratories Limited), Yasuo Hidaka (Fujitsu Laboratories of America, Inc.), Kenichi Kawai (Fujitsu Limited), Michael Lee (Fujitsu Laboratories of America, Inc.), Mark Lionbarger (Fujitsu Laboratories of America, Inc.), Daisuke Mizutani (Fujitsu Laboratories LTD.), Yasushi Mizutani (Fujitsu Limited), Hideaki Nagaoka (Fujitsu Laboratories Limited), Tetsuro Yamada (Fujitsu Advanced Technologies Limited), Takuji Yamamoto (Fujitsu Laboratories of America, Inc.)

Modeling and Analysis of Differential vs. Single-ended Signaling with Through-Silicon Vias (TSVs) for Low-power/High-speed 3D IC channel design
Wendem Beyene (Rambus Inc.), Joohee Kim (Rambus Inc.), Hai Lan (Rambus Inc.)

Moving Towards the Light, a Photonic Extensions API for OpenAccess
Susan Carver (Integration Initiative), Pieter Dumon (Luceda Photonics), Martin Fiers (Luceda Photonics), Kevin Nesmith (Silicon Integration Initiative)

My Product Failed EMI - Now What Do I Do?
Kenneth Wyatt (Wyatt Technical Services LLC)

Near-Field Magnetic Probe Method - Evanescent and Propagating Mode Measurements
Daniel Brooks (APREL Inc.)

New De-embedding Techniques for PCB Transmission-Line Characterization
James Drewniak (MIssouri S&T), Jun Fan (MIssouri S&T), Xiaoning Ye (Intel Corp)

New Metric Offers More Accurate Estimate Of Optical Transmitter's Impact On Multi-Mode Fiber-Optic Links
Greg D. Le Cheminant (Keysight Technologies), Piers Dawe (Mellanox Technologies), John Petrilla (Avago Technologies)

One-Sided Measurement of Power Supply Impedance Without Connectors
Joachim Held (Siemens AG), Richard Sjiariel (CST)

Optimization of PCB Capacitors for Signal Integrity Performance in Mixed Reference Channels
Darryl Kostka (CST of America), Selman Ozbayat (Qualcomm Technology Inc.), Gerardo Romo Luevano (Qualcomm Technology Inc.), Martin Schauer (CST of America)

Optimizing Symmetry in Open Field Designs
Gary Biddle (Samtec, Inc), Julian Ferry (Samtec, Inc)

Package Simulations For Mitigating Noise Coupling Onto Sensitive RF Signals
Dmitry Fliter (CSR), Nir Malka (CSR)

Passive 28G Precision ISI Channel to Assess DFE Effectiveness Empirically
Martin Spadaro (Vitesse Semiconductor)

PCB Layout Checking Methodology to Capture Power to I/O Coupling Issues
Patt Chang (Intel), Jin Fang (Intel), Jimmy Hsu (Intel), Falconee Lee (Intel), YL Li (Intel Corp.), Gong Ouyang (Intel), Yinglei Ren (Intel), Thonas Su (Intel), Kai Xiao (Intel), Xiaoning Ye (Intel Corp)

PCB Material and Copper Foil Considerations for Insertion Loss
Brandon Gore (Intel), Gary Long (Intel Corp.), Jeff Loyer (Intel Corp.)

PDN Modeling in the Presence of Multiple Power and "Ground" Pins
Kit Ma (Qualcomm Technologies Inc.), Timothy Michalka (Qualcomm Technologies Inc.), Javid Mohamed (Qualcomm Technologies Inc.), Gerardo Romo Luevano (Qualcomm Technologies Inc.)

Power Delivery Noise and its Impact on Jitter and System Margin for Multi-Gb/s High-Speed Serial Interfaces
Almario F. Delos (Intel Corporation), Xiaoping Liu (Intel Corporation), Vishram Pandit (Intel Corporation), Mackenzie R Scott (Intel Corporation)

Power Measurements For EMI/EMC Testing
Vitali Penso (Wireless Telecom Group)

Power Referenced Design - How Bad is Not So Bad?
Sherman Chen (EMC)

Practical Method for Modeling Conductor Surface Roughness Using Close Packing of Equal Spheres
Bert Simonovich (Lamsim Enterprises Inc.)

Rigid-Flex PCB Right The First Time - Without Paper Dolls
Benjamin Jordan (Altium Inc.)

SerDes steady state adaptation challenges over PVT in existing SAS/SATA and emerging PCIe Gen4/SAS4 application and their solutions with real time pattern discriminator constrained adaptation
Amaresh Malipatil (Avago Technologies), Weiwei Mao (Avago Technologies), Mohammad Mobin (Avago Technologies), Aravind Nayak (Avago Technologies), Sunil Srinivasa (Avago Technologies), Dr. Haitao (Tony) Xia (Avago Technologies)

Signal Integrity Challenges and Solutions for Next-Generation OIF CEI-56G-MR "Chip-to-Chip" and "Chip-to-Module" Interfaces
Philip Fisher (Avago Technologies), Edward Frlan (Semtech), Mike Peng Li (Altera), Cathy Liu (Avago Technologies)

Signaling Study for Massively Parallel Interface for SiP, Silicon Interposer, or On-Chip Communications
Karthik Chandrasekar (Altera), Guang Chen (Altera), Dan Oh (Altera), Changwook Yoon (Altera)

Simplified De-Embedding Techniques: Some Effects Of Match And Geometry Assumptions Jon Martens (Anritsu)
Simulating and Measuring Microohms in PDNs
Jae Young Choi (Oracle Corporation), Istvan Novak (Oracle Corporation)

Spec-Based Behavior Modeling for High Speed SerDes I/O Systems
Todd Bermensolo (Intel Corporation), Dan Crain (Intel Corporation), Zao Liu (Intel Corporation), Carlos Lizalde (Intel Corporation), Cesar Mendez-ruiz (Intel Corporation)

Stability of Various Lock Detection Algorithms for Bang-Bang CDRs
David Banas (Altera Corp.)

Statistical Principles and Trends in Mask Testing
Maria Agoston (Tektronix), Ron Henricksen (Tektronix), Richard Poulo (Tektronix), Pavel Zivny (Tektronix)

Substrate Noise Full-Chip Level Analysis Flow From Early Design Stages Till Tapeout
Hagay Guterman (CSR), Jerome Toublanc (ANSYS)

System Power Integrity
Larry Smith (Qualcomm), Steve Weir (IPBlox, LLC), Iliya Zamek (IZ_consulting)

Target Impedance Limitations and Rogue Wave Assessments on PDN Performance
Steve Sandler (Picotest)

The Role of Signal Integrity Practices in Optical Design Qualification
Brice Achkir (Cisco Systems), Paul Brooks (JDSU), Chris Cole (Finisar), Greg D. Le Cheminant (Keysight Technologies), Edward Frlan (Semtech), Pavel Zivny (Tektronix)

Theoretical and Experiment Investigations for the Jitter Induced by Transmitter Equalizations
Mike Peng Li (Altera), Timothy Lu (Altera), Masashi Shimanouchi (Altera), Hsinho Wu (Altera)

Topology Performance Comparison using eGaN FETs in 6.78 MHz Highly Resonant Wireless Power Transfer
Michael de Rooij (Efficient Power Conversion), Johan Strydom (Efficient Power Conversion)

Ultrascale DDR4 De-Emphasis and CTLE Feature Optimization with Statistical Engine for BER Specification
Nilesh Kamdar (Keysight Technologies), Penglin Niu (Xilinx), Gary Otonari (Keysight Technology), Fangyi Rao (Keysight Technologies), Juan Wang (Xilinx)

Ultrascale FPGA DDR4 2400 Mbps System Level Design Optimization and Validation
Dmitry Klokotov (Xilinx), Wei Liu (Xilinx), Penglin Niu (Xilinx), Thomas To (Xilinx)

Understanding IBIS-AMI Simulations
Douglas Burns (SiSoft), John Madsen (SiSoft), Todd Westerhoff (SiSoft)

Understanding the Effects of Channel Generated Skew on Chassis EMI
Michael Fogg (FCI LLC USA)

Using Microprobing, Modeling and Error Correction Techniques to Optimize Channel Design"
Mike Resso (Keysight Technologies), Miki Takahashi (Granite River Labs)

Validation Of How Power/Ground Bump Reduction Decreases Average Power And Supply Noise
Kyoungchoul Koo (Samsung Electronics), Youngsoo Lee (Samsung Electronics), Dongyoun Yi (Samsung Electronics)

Vectorless Prediction of Simultaneous Switching Noise from FPGAs
Chunchun Sui (Missouri University of Science and Technology)

What Makes a Good 25Gbps Channel? COM vs. BER Metrics
Davi Correia (Molex), IL-Young Park (Cisco), Michael Rowlands (Molex)

Wireless 101/201: Intro to RF & Microwave/Advanced Communication Systems Neil Jarvis (Rohde and Schwarz)